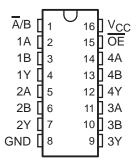
# SN54HCT257, SN74HCT257 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS WITH 3-STATE OUTPUTS

SCLS072D - NOVEMBER 1988 - REVISED SEPTEMBER 2003

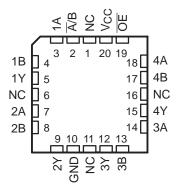
- Operating Voltage Range of 4.5 V to 5.5 V
- High-Current 3-State Outputs Interface Directly With System Bus
- Typical t<sub>pd</sub> = 17 ns
- Low Power Consumption, 80-μA Max I<sub>CC</sub>
- ±6-mA Output Drive at 5 V

SN54HCT257 . . . J PACKAGE SN74HCT257 . . . D OR N PACKAGE (TOP VIEW)



- Low Input Current of 1 μA Max
- Inputs Are TTL-Voltage Compatible
- Provide Bus Interface From Multiple Sources in High-Performance Systems
- Buffered Inputs and Outputs

# SN54HCT257 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

## description/ordering information

The 'HCT257 devices are designed to multiplex signals from 4-bit data sources to 4-output data lines in bus-organized systems. The 3-state outputs do not load the data lines when the output-enable  $(\overline{OE})$  input is at the high logic level.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

#### ORDERING INFORMATION

TA	PACKAC	3E†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 25	SN74HCT257N	SN74HCT257N
4000 4- 0500		Tube of 40	SN74HCT257D	
-40°C to 85°C	SOIC - D	Reel of 2500	SN74HCT257DR	HCT257
		Reel of 250	SN74HCT257DT	
5500 to 40500	CDIP – J	Tube of 25	SNJ54HCT257J	SNJ54HCT257J
–55°C to 125°C	LCCC - FK	Tube of 55	SNJ54HCT257FK	SNJ54HCT257FK

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

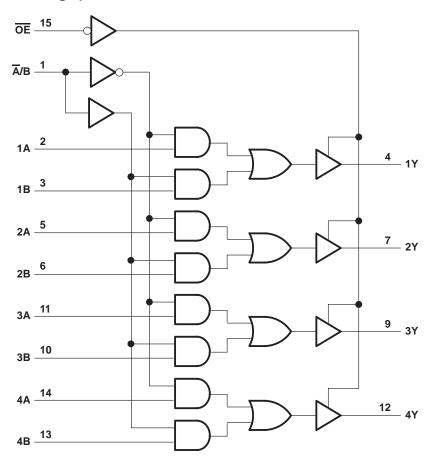


SCLS072D - NOVEMBER 1988 - REVISED SEPTEMBER 2003

#### **FUNCTION TABLE**

	INPUTS										
ŌĒ	SELECT	DA	TA	OUTPUT							
OE	A/B	Α	В	·							
Н	Х	Х	Х	Z							
L	L	L	X	L							
L	L	Н	X	Н							
L	Н	Χ	L	L							
L	Н	Χ	Н	Н							

# logic diagram (positive logic)



Pin numbers shown are for the D, J, and N packages.



# SN54HCT257, SN74HCT257 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS WITH 3-STATE OUTPUTS

SCLS072D - NOVEMBER 1988 - REVISED SEPTEMBER 2003

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>	–0.5 V to 7 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see Note 1)	±20 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) (see Note 1)	±20 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	±35 mA
Continuous current through V <sub>CC</sub> or GND	±70 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2): D package	
N package	
Storage temperature range, T <sub>Stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### recommended operating conditions (see Note 3)

			SN	54HCT2	57	SN	74HCT2	57	LINUT
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	2	Į.	7/	2			V
VIL	Low-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V		77	0.8			0.8	V
VI	Input voltage		0	1	VCC	0		VCC	V
VO	Output voltage		0	2	Vcc	0		VCC	V
t <sub>t</sub>	Input transition (rise and fall) time		000	5	500			500	ns
TA	Operating free-air temperature		-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

24244555	7507.00	NETIONS	.,	Т	A = 25°C	;	SN54H	CT257	SN74H	CT257	
PARAMETER	TEST CO	NDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
V	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	$I_{OH} = -20  \mu A$	45.1/	4.4	4.499		4.4		4.4		
VOH	VI = VIH or VIL	$I_{OH} = -6 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		٧
, ,	\ \ \\ a=\\	I <sub>OL</sub> = 20 μA	45.1/		0.001	0.1		0.1		0.1	V
VoL	$V_I = V_{IH}$ or $V_{IL}$	I <sub>OL</sub> = 6 mA	4.5 V		0.17	0.26		0.4		0.33	V
lį	$V_I = V_{CC}$ or 0		5.5 V		±0.1	±100		±1000		±1000	nA
loz	$V_O = V_{CC}$ or 0,	$V_I = V_{IH}$ or $V_{IL}$	5.5 V		±0.01	±0.5	4	±10		±5	μΑ
Icc	$V_I = V_{CC}$ or 0,	I <sub>O</sub> = 0	5.5 V			8	37/	160		80	μΑ
∆I <sub>CC</sub> ‡	One input at 0.5 V Other inputs at 0 or		5.5 V		1.4	2.4	PRO	3		2.9	mA
Ci			4.5 V to 5.5 V		3	10		10*		10	pF

<sup>\*</sup> On products compliant to MIL-PRF-38535, this parameter is not production tested.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>2.</sup> The package thermal impedance is calculated in accordance with JESD 51-7.

<sup>‡</sup>This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or V<sub>CC</sub>.

# SN54HCT257, SN74HCT257 QUADRUPLE 2-LINE TO 1-LINE DATA SELECTORS/MULTIPLEXERS WITH 3-STATE OUTPUTS

SCLS072D - NOVEMBER 1988 - REVISED SEPTEMBER 2003

# switching characteristics over recommended operating free-air temperature range, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

	FROM	то	,,	T	λ = 25°C	;	SN54H	CT257	SN74H	CT257	
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
	A or D	V	4.5 V		20	30		45		38	
	A or B	Y	5.5 V		17	27		40		34	
<sup>t</sup> pd	Ā/B	V	4.5 V		20	30		45		38	ns
	A/B	Y	5.5 V		17	27		40		34	
	ŌĒ		4.5 V		20	30		45		38	
<sup>t</sup> en	OE	Y	5.5 V		17	27	(0)	40		34	ns
	ŌĒ	Y	4.5 V		20	30	$g_{Q_{\zeta}}$	45		38	
<sup>t</sup> dis	OE	Y	5.5 V		17	27	) Y <sub>G</sub>	40		34	ns
4.		Any	4.5 V	·	8	15		22		19	20
t <sub>t</sub>		Any	5.5 V		7	14		21		17	ns

# switching characteristics over recommended operating free-air temperature range, $C_L$ = 150 pF (unless otherwise noted) (see Figure 1)

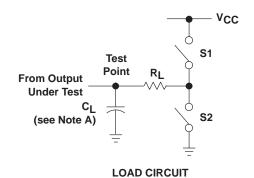
	FROM	то	.,	T,	λ = 25°C	;	SN54HCT257	SN74HCT257	
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN MAX	MIN MAX	UNIT
	A D	V	4.5 V		22	38	57	48	
	A or B	Y	5.5 V		19	35	53	44	
<sup>t</sup> pd	<sup>t</sup> pd ————————————————————————————————————	V	4.5 V		22	38	57	48	ns
	A/B	Y	5.5 V		19	35	53	44	
	ŌĒ	V	4.5 V		23	40	5 60	50	
<sup>t</sup> en	OE .	Y	5.5 V		20	38	57	48	ns
4.		Any	4.5 V		17	42	63	53	no
t <sub>t</sub>		Any	5.5 V		14	38	57	48	ns

# operating characteristics, T<sub>A</sub> = 25°C

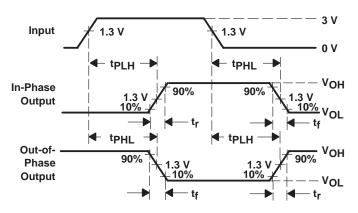
	PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance	No load	13	pF

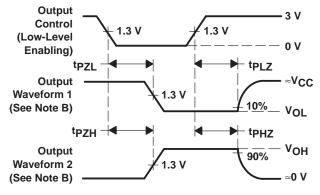
SCLS072D - NOVEMBER 1988 - REVISED SEPTEMBER 2003

#### PARAMETER MEASUREMENT INFORMATION



PARAM	/IETER	RL	CL	S1	S2
	<sup>t</sup> PZH	<b>1 k</b> Ω	50 pF or	Open	Closed
t <sub>en</sub>	tPZL	1 K22	150 pF	Closed	Open
4	. tpHZ 4		50 pF	Open	Closed
<sup>t</sup> dis	tPLZ	<b>1 k</b> Ω	50 pr	Closed	Open
t <sub>pd</sub> or	tpd or tt		50 pF or 150 pF	Open	Open





VOLTAGE WAVEFORMS
OUTPUT AND 3-STATE BIDIRECTIONAL I/O
PROPAGATION DELAY TIME

VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES FOR 3-STATE OUTPUTS

NOTES: A. C<sub>L</sub> includes probe and test-fixture capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>f</sub> = 6 ns, t<sub>f</sub> = 6 ns.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. tpl 7 and tpH7 are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms





23-Aug-2017

#### PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
SN74HCT257D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HCT257	Samples
SN74HCT257DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HCT257	Samples
SN74HCT257DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HCT257	Samples
SN74HCT257DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	HCT257	Samples
SN74HCT257N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 85	SN74HCT257N	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: Til defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.



## **PACKAGE OPTION ADDENDUM**

23-Aug-2017

**Important Information and Disclaimer:** The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



#### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

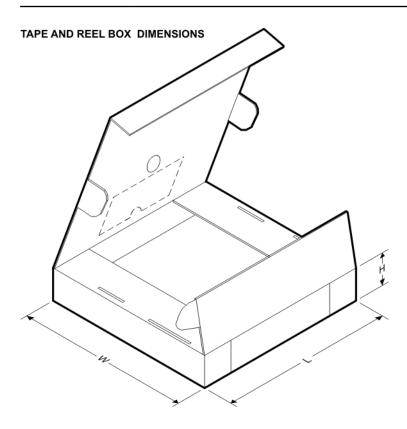
### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device		Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HCT257DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1





#### \*All dimensions are nominal

Ī	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
	SN74HCT257DR	SOIC	D	16	2500	333.2	345.9	28.6

# N (R-PDIP-T\*\*)

# PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



# D (R-PDS0-G16)

### PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



# D (R-PDSO-G16)

# PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



#### **IMPORTANT NOTICE**

Texas Instruments Incorporated (TI) reserves the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete.

TI's published terms of sale for semiconductor products (http://www.ti.com/sc/docs/stdterms.htm) apply to the sale of packaged integrated circuit products that TI has qualified and released to market. Additional terms may apply to the use or sale of other types of TI products and services.

Reproduction of significant portions of TI information in TI data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such reproduced documentation. Information of third parties may be subject to additional restrictions. Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyers and others who are developing systems that incorporate TI products (collectively, "Designers") understand and agree that Designers remain responsible for using their independent analysis, evaluation and judgment in designing their applications and that Designers have full and exclusive responsibility to assure the safety of Designers' applications and compliance of their applications (and of all TI products used in or for Designers' applications) with all applicable regulations, laws and other applicable requirements. Designer represents that, with respect to their applications, Designer has all the necessary expertise to create and implement safeguards that (1) anticipate dangerous consequences of failures, (2) monitor failures and their consequences, and (3) lessen the likelihood of failures that might cause harm and take appropriate actions. Designer agrees that prior to using or distributing any applications that include TI products, Designer will thoroughly test such applications and the functionality of such TI products as used in such applications.

TI's provision of technical, application or other design advice, quality characterization, reliability data or other services or information, including, but not limited to, reference designs and materials relating to evaluation modules, (collectively, "TI Resources") are intended to assist designers who are developing applications that incorporate TI products; by downloading, accessing or using TI Resources in any way, Designer (individually or, if Designer is acting on behalf of a company, Designer's company) agrees to use any particular TI Resource solely for this purpose and subject to the terms of this Notice.

TI's provision of TI Resources does not expand or otherwise alter TI's applicable published warranties or warranty disclaimers for TI products, and no additional obligations or liabilities arise from TI providing such TI Resources. TI reserves the right to make corrections, enhancements, improvements and other changes to its TI Resources. TI has not conducted any testing other than that specifically described in the published documentation for a particular TI Resource.

Designer is authorized to use, copy and modify any individual TI Resource only in connection with the development of applications that include the TI product(s) identified in such TI Resource. NO OTHER LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE TO ANY OTHER TI INTELLECTUAL PROPERTY RIGHT, AND NO LICENSE TO ANY TECHNOLOGY OR INTELLECTUAL PROPERTY RIGHT OF TI OR ANY THIRD PARTY IS GRANTED HEREIN, including but not limited to any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information regarding or referencing third-party products or services does not constitute a license to use such products or services, or a warranty or endorsement thereof. Use of TI Resources may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

TI RESOURCES ARE PROVIDED "AS IS" AND WITH ALL FAULTS. TI DISCLAIMS ALL OTHER WARRANTIES OR REPRESENTATIONS, EXPRESS OR IMPLIED, REGARDING RESOURCES OR USE THEREOF, INCLUDING BUT NOT LIMITED TO ACCURACY OR COMPLETENESS, TITLE, ANY EPIDEMIC FAILURE WARRANTY AND ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, AND NON-INFRINGEMENT OF ANY THIRD PARTY INTELLECTUAL PROPERTY RIGHTS. TI SHALL NOT BE LIABLE FOR AND SHALL NOT DEFEND OR INDEMNIFY DESIGNER AGAINST ANY CLAIM, INCLUDING BUT NOT LIMITED TO ANY INFRINGEMENT CLAIM THAT RELATES TO OR IS BASED ON ANY COMBINATION OF PRODUCTS EVEN IF DESCRIBED IN TI RESOURCES OR OTHERWISE. IN NO EVENT SHALL TI BE LIABLE FOR ANY ACTUAL, DIRECT, SPECIAL, COLLATERAL, INDIRECT, PUNITIVE, INCIDENTAL, CONSEQUENTIAL OR EXEMPLARY DAMAGES IN CONNECTION WITH OR ARISING OUT OF TI RESOURCES OR USE THEREOF, AND REGARDLESS OF WHETHER TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES.

Unless TI has explicitly designated an individual product as meeting the requirements of a particular industry standard (e.g., ISO/TS 16949 and ISO 26262), TI is not responsible for any failure to meet such industry standard requirements.

Where TI specifically promotes products as facilitating functional safety or as compliant with industry functional safety standards, such products are intended to help enable customers to design and create their own applications that meet applicable functional safety standards and requirements. Using products in an application does not by itself establish any safety features in the application. Designers must ensure compliance with safety-related requirements and standards applicable to their applications. Designer may not use any TI products in life-critical medical equipment unless authorized officers of the parties have executed a special contract specifically governing such use. Life-critical medical equipment is medical equipment where failure of such equipment would cause serious bodily injury or death (e.g., life support, pacemakers, defibrillators, heart pumps, neurostimulators, and implantables). Such equipment includes, without limitation, all medical devices identified by the U.S. Food and Drug Administration as Class III devices and equivalent classifications outside the U.S.

TI may expressly designate certain products as completing a particular qualification (e.g., Q100, Military Grade, or Enhanced Product). Designers agree that it has the necessary expertise to select the product with the appropriate qualification designation for their applications and that proper product selection is at Designers' own risk. Designers are solely responsible for compliance with all legal and regulatory requirements in connection with such selection.

Designer will fully indemnify TI and its representatives against any damages, costs, losses, and/or liabilities arising out of Designer's non-compliance with the terms and provisions of this Notice.